

SINGLE CHIP TELETEXT DECODER FOR 625 LINE OPERATION

(Supersedes version in April 1994 Consumer IC Handbook, HB3120-2.0)

The MV1817 Television Data Service, TDS, IC incorporates all the features of the MV1815 with identical registers, so that MV1815 register control is software compatible. Additional TDS features are controlled by registers with addresses above those of the MV1815. A 2K/page system is included to enable extension packets to be stored with the display page data and page header data.

FEATURES

Acquisition

- Two page related data acquisition circuits
- On chip adaptive slicers for data and sync
- Accepts all data packets
- Advanced Header and Instant Page Clear working

Display

- High resolution 15x10 pixel characters
- Multi-lingual capability
- 26 display rows

Memory

- Up to 510 pages in one 4 bit organised DRAM
- 2K or 1K bytes per page

Synchronisation

- Three vertical time base modes:-
 - 3121/2-3121/2 interlaced
 - 312 312 non-interlaced default
 - 312 313 non-interlaced
- Line (H) and field (V) sync inputs
- Full field operation
- On chip video switch

I²C bus etc.

- I²C bus interface bus to microcontroller
- I²C bus is released during power down
- Software compatible with MV1815
- Software maskable EVENT interrupts
- Register to indicate language variant

ORDERING INFORMATION

MV1817–3 CG DPAS – All Europe version MV1817–3 CG GPBR – All Europe version

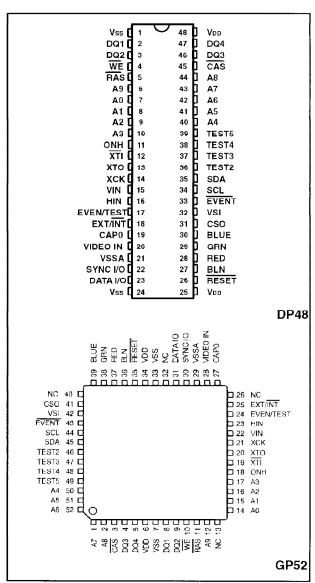


Fig. 1 Pin connections - top view

ABSOLUTE MAXIMUM RATINGS

Supply voltage -0.3V to +7.0V
All inputs -0.3V to V_{DD}+0.3V
Operating temperature 0°C to +70°C
Storage temperature -65°C to 150°C

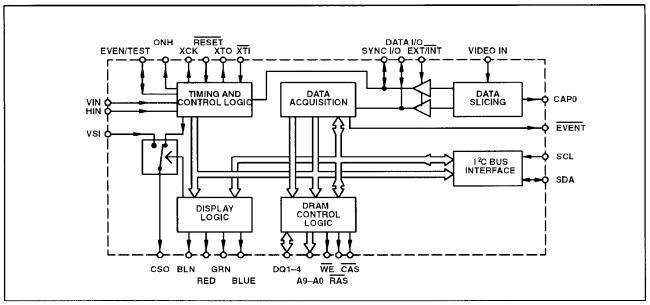


Fig. 2 Functional block diagram

CRYSTAL SPECIFICATION

Parallel resonant fundamental

frequency (preferred)

Tolerance over operating

1.50

6.93750MHz. AT cut

temperature range

+50ppm

Tolerance overall

±100ppm

Nominal load capacitance

30pF

Equivalent series resistance

<20 Ω

ELECTRICAL CHARACTERISTICS

 T_{amb} = 0°C to +70°C, V_{DD} = +5V \pm 10%. These characteristics are guaranteed by either production test or design. They apply within the specified ambient temperature and supply voltage ranges unless otherwise stated.

21			Value				
Characteristics	Pin	Min	Тур	Max	Units	Conditions	
Supply voltage	25, 48	4.5	5.0	5.5	V		
Supply current	25, 48		80	140	mA	V _{DD} =5.5V White test screen	
Video input, VSI	20, 32					Acquisition from TV lines 6–22 and 318–335	
Voltage amplitude		0.7	1.0	2.0	V _{pp}	Bottom of sync to white (pk to pk)	
Source impedance				250	Ω	220nF input capacitor	
CAP0	19						
Capacitor value			220		nF	Connected to GND	
Capacitor tolerance		10%		+10%			
Effective series resistance				5	Ω	1MHz	
Sync I/O & Data I/O	22, 23					Acquisition from TV lines 2–22 and 314–335, see note 1.	
Output voltage High (Data I/O only)		0.8V _{DD}	0.9V _{DD}		V	I _{OH} =-2.0mA Sync I/O is an open drain output.	
Output voltage Low			0.2	0.4	V	I _{OL} =2.0mA	
Input voltage Low		0		0.2V _{DD}	V		
Input voltage High		0.8V _{DD}		V _{DD}	V		
Input current Low		-1 0		+10	μА	V _{IN} =V _{SS} or V _{DD}	

ELECTRICAL CHARACTERISTICS (cont.)

Tamb= 0°C to +70°C, VDD=+5V +10%. These characteristics are guaranteed by either production test or design. They apply within the specified ambient temperature and supply voltage ranges unless otherwise stated.

]	Value			
Characteristics	Pin	Min	Тур	Max	Units	Conditions
EXT/INT	18					75k (nom) pull-down resistor
Input voltage Low		0		0.2V _{DD}	V	
Input voltage High		0.8V _{DD}		V_{DD}	V	
Input current Low		-10		+10	μA	V _{IN} =V _{SS}
Input current High		18	67	275	μА	$V_{IN}=V_{DD}$
XTI input	12					1M (nom) resistor to XTO
Input voltage Low		0		0.2V _{DD}	V	
Input voltage High		0.8V _{DD}		V _{DD}	V	
Input current Low		-0.5	-5.0	-20	μΑ	-0.3 <v<sub>IN<v<sub>IL max</v<sub></v<sub>
Input current High		0.5	1.5	20	μΑ	$V_{IH} \min \langle V_{IN} \langle (V_{DD} + 0.3) \rangle$
XTO output	13				1	
Output voltage High		0.8V _{DD}	0.9V _{DD}		V	I _{OH} =-0.1mA
Output voltage Low			0.2	0.4	V	I _{OL} =0.1mA
Frequency			6.9375		MHz	±100ppm
I ² C bus SCL, SDA Schmitt inputs	34, 35					
Input voltage Low		0		1.5	V	
Input voltage High		3.0		V _{DD}	V	
Output voltage Low			0.1	0.6	v	I _{OL} =6.0mA
SCL Clock Frequency			750	775	kHz	
Hysteresis voltage	}	ľ	0.4		V	
EVENT	33					75k (nom) pull-up resistor
Output voltage Low			0.2	0.4	V	I _{OL} =6.0mA open drain
RESET, Schmitt input	26					75k (nom) pull-up resistor
Threshold voltage falling		1.4	1.9			
Threshold voltage rising			3.1	3.8	V	
Hysteresis voltage			1.2		V	
Input current Low		-18	-67	275	μΑ	$V_{IN}=V_{SS}$
Input current High		-10		+10	μΑ	$V_{IN}=V_{DD}$
VIN, HIN, Schmitt input	15, 16				,	IIV BB
Threshold voltage falling		1.4	1.9			
Threshold voltage rising			3.1	3.8	V	
Hysteresis voltage	1		1.2		V	
Input current Low	1	-10		+10	μΑ	$V_{IN}=V_{SS}$
Input current High		– 10		+10	μΑ	$V_{IN}=V_{DD}$
VIN pulse width		32			μs	
HIN pulse width		1			μs	at 90% level
VIN rise time				18	μs	10% to 90% level
HIN rise time				6	μs	10% to 90% level

ELECTRICAL CHARACTERISTICS (cont.) $T_{amb} = 0^{\circ}\text{C to } 1.70^{\circ}\text{C}, V_{DD} = 1.5\text{V} \pm 10\%. \text{ These characteristics are guaranteed by either production test or design. They apply within the specified ambient temperature and supply voltage ranges unless otherwise stated.}$

	T		Value			
Characteristics	Pin	Min	Тур	Max	Units	Conditions
ONH, XCK	11, 14					See note 2
Output voltage High		0.8V _{DD}	0.9V _{DD}		V	I _{OH} =-2.0mA
Output voltage Low			0.2	0.4	V	I _{OL} =2.0mA
Red, Green, Blue	28, 29					
Output voltage High	30	0.9V _{DD}	0.95V _{DD}		V	I _{OH} =-8mA
Output voltage Low			0.2	0.4	V	I _{OL} =8mA
Tri-state leakage current		-10		10	μΑ	
Blank	27					
Output voltage High		0.8V _{DD}	0.9V _{DD}		V	I _{OH} =-12mA
Output voltage Low			0.2	0.4	V	I _{OL} =12mA
CSO	31					With typical ac load of 360Ω
Output voltage swing		0.1		1.5	V _{PP}	Text mode only. See note 3
Output voltage High		0.8V _{DD}	0.9V _{DD}		V	I _{OH} =-0.2mA with CSOT bit =1
Output voltage Low			0.2	0.4	V	I _{OL} =1.6mA with CSOT bit =1
Even output/Test input (Schmitt)	17					75k (nom) pull-down resistor
Output voltage High		0.8V _{DD}	0.9V _{DD}		V	I _{OH} =-2.0mA
Output voltage Low			0.2	0.4	V	I _{OL} =2.0mA
Threshold voltage falling		1.4	1.9			
Threshold voltage rising			3.1	3.8	V	
Hysteresis voltage		0.6	1.2		V	
Input current Low		-10		-10	μΑ	V _{IN} =V _{SS}
Input current High		18	67	275	μΑ	$V_{IN}=V_{DD}$
Data DQ1 DQ4	2, 3					75k (nom) pull-up resistor
Output voltage High	46, 47	0.8V _{DD}	0.9V _{DD}		V	I _{OH} =-2.0mA
Output voltage Low			0.2	0.4	V	I _{OL} =2.0mA
Input voltage Low		0		0.8	\ \ \	
Input voltage High		2.0		V _{DD}	V	
Input current Low		-18	- 67	-275	μА	V _{IN} =V _{SS}
Input current High		-10		+10	μΑ	$V_{IN}=V_{DD}$
Address A0 – A9	4 – 10					See note 4
RAS, CAS, WE	40 – 45					
Output voltage High		0.8V _{DD}	0.9V _{DD}	:	V	I _{OH} = -2.0mA
Output voltage Low			0.2	0.4	V	I _{OL} =2.0mA

NOTE1. Acquisition window is wider when sliced data is supplied to DATA I/O to accommodate satellite transmissions. XCK output will be 6.9375MHz with XCKH=0 in register TADD, or 13.875Mhz with XCKH=1.

NOTE 2

NOTE 3. CSO output voltage when in Picture or Mix modes will depend on the size of the video signal applied to VSt pin 32, together with the attenuation due to the internal video switch (30Ω nom) and the external load on pin 31. In these modes the video signal at pin 32 is switched straight through to pin 31. The maximum current allowed through the video switch is 24 mA.

NOTE 4. Capacitive loading on $\overline{\mbox{RAS}}$ and $\overline{\mbox{CAS}}$ should not exceed 20pF per pin.

Pin N0	Name	Pin Description
1, 24	V _{SS}	Power ground 0V, both pins must be connected.
2, 3, 46, 47	DQ1-4	DRAM data lines, with internal 75k pull-up resistors.
4	WE	DRAM write enable.
5	RAS	DRAM row address strobe.
6-10, 40-44	A9, A0-8	DRAM address outputs.
11	ONH	On hours output.
12	XTI	Crystal input or external clock input.
13	XTO	Crystal output.
14	XCK	Divided output of VCO clock, default 6.9375MHz. If XCKH bit in TADD register is set high, the output is 13.875MHz.
15	VIN	Vertical sync input positive pulse. If bit VINV in MODE register is set high, the signal may be a negative pulse.
16	HIN	Horizontal sync input positive pulse. If bit HINV in MODE register is set high, the signal may be a negative pulse.
17	EVEN/TEST	Even output is enabled by bits IOE and EOE in SYNCSW register. If EVEN output is not used it should be left open circuit. TEST input is used for factory testing. An internal 75k pull-down resistor is included.
18	EXT/INT	Control pin for SYNC I/O and DATA I/O, with internal 75k pull-down. When high, supply sliced sync and data.
19	CAPO	Black level reference capacitor.
20	VIDEO IN	PAL composite signal with negative syncs.
21	VSSA	Analog ground.
22	SYNC I/O	Sliced sync input/output, (open drain output).
23	DATA I/O	Sliced data input/output, (pushpull output).
25, 48	V _{DD}	Power, +4.5V to +5.5V, both pins must be connected.
26	RESET	Active low reset input, with 75k pull up-resistor.
27	BLN	Blanking output, high power push-pull driver.
28	RED	Red output, high power push-pull tri-state driver.
29	GRN	Green output, high power push-pull tri-state driver.
30	BLUE	Blue output, high power push-pull tri-state driver.
31	CSO	Composite sync output generated in text modes. In picture modes, connected to VSI through $<30\Omega$ video switch, see Fig. 6.
32	VSI	Composite video switch input.
33	EVENT	Active low open drain output interrupt to microcontroller, with internal 75k pull-up.
34	SCL	Standard I ² C bus serial clock input.
35	SDA	Standard I ² C bus serial data input/output. Address is 0010 001R/W (22hex).
36	TEST2	For factory test only, do not connect.
37	TEST3	For factory test only, do not connect.
38	TEST4	For factory test only, do not connect.
39	TEST5	for factory test only, do not connect.
45	CAS	DRAM column address strobe.

PINS	TEST	TEST LEVELS	NOTES
SDA &SCL	Human body model	1kV on 100p K through 1k5Ω	<15% LTPD
SDA & SCL	Machine model	100V on 200pF through 0Ω & <500nH	
All others	Human body model	2kV on 100pF through 1k5Ω	Meets Mil Std. 883D class 2 requirements
All others	Machine model	200V on 200pF through 0Ω & <500nH	

LTPD=Lot Tolerant Percent Defective

ADDRESS dec/hex	REGISTER NAME	7	6	5	4	3	2	1	0	R/W	DEFAULT hex
	RADD	A17	A16	IAI	RA4	RA3	RA2	RA1	RA0	W	00
				:							
0/0	ACONA	ACQ	MGC	PBC	PAC	SDC	scc	SBC	SAC	w	F0
1/1	STORA	STA7	STA6	STA5	STA4	STA3	STA2	STA1	STA0	W	02
2/2	PGS1A	SCS3	SCS2	SCS1	SCS0	SAS3	SAS2	SAS1	SAS0	w	00
3/3	PGS2A	MS2	MS1	MS0	SDS1	SDS0	SBS2	SBS1	SBS0	w	20
4/4	PGS3A	PBS3	PBS2	PBS1	PBS0	PAS3	PAS2	PAS1	PAS0	W	00
5/5	ACONB	HLD	MGC	PBC	PAC	SDC	scc	SBC	SAC	w	F0
6/6	STORB	STB7	STB6	STB5	STB4	STB3	STB2	STB1	STB0	w	03
7/7	PGS1B	SCS3	SCS2	SCS1	SCS0	SAS3	SAS2	SAS1	SAS0	W	00
8/8	PGS2B	MS2	MS1	MS0	SDS1	SDS0	SBS2	SBS1	SBS0	w	00
9/9	PGS3B	PBS3	PBS2	PBS1	PBS0	PAS3	PAS2	PAS1	PAS0	w	88
10/A	RECON	WIO	W124	WI25	PINB	PINA	FF	CDB	CDA	w	00
1 1/B	DISCON1	INV	RLH	DSB	CLS	CUR	BLC	LS3	UDI	w	00
12/C	DISCON2	LS0	LS1	LS2	MGS	IHD	SPH	BX1	BX0	w	00
13/D	DISCON3	TXT	MIX	INT	REV	UDK	SPOS	ST2	ST1	w	00
14/E	DISCON4	BXP	вхн	BXT	BXS	DHT	DHB	SG2	SG1	w	00
15/F	HADD	A15	A14	A13	A12	A11	A10	А9	A8	w	00
16/10	LADD	A7	A6	A5	A4	АЭ	A2	A1	Α0	w	00
17/11	WDATA	WD7	WD6	WD5	WD4	MD3	WD2	WD1	WD0	w	00
19/13	SCROLL	WI29	M∀	CRL	SRA4	SRA3	SRA2	SRA1	SRA0	w	00
20/14	SYNCSW	ESS	_	BXSDEL	CSOT	IOE	EOE	SEN	svs	w	00
21/15	MODE	MD3	MD2	MD1	312:313	VHLD	HVEN	HINV	VINV	w	24
22/16	TADD	_	A18	RESET	хскн	2K/ST	DISC	ADEC	DST8	w	00
23/17	DISPST	DSTI7	DST6	DST5	DST4	DST3	DST2	DST1	DST0	w	00
24/18	DPOS	V3	V2	V1	VO	НЗ	H2	H1	но	w	7B
25/19	ENABLE	NPR	VHR	830	X/24A	X/28	X/27	X/26	X/24B	w	EE
26/1A	ACCENT	APA	APB	C8APIA	C8APIB	SCAPIA	SCAPIB	-	AHEN	w	00
0/0	EVENTA	NPR	VHR	830A	X/24	X/28	X/27	X/26	C8	R	-
1/1	EVENTB	NPR	VHR	830B	X/24	X/28	X/27	X/26	C8	R	-
2/2	CBITSA	C14	C13	C12	C11	C10	C7	C6	C5	R	-
3/3	PGR1A	SCR3	SCR2	SCR1	SCR0	SAR3	SAR2	SAR1	SAR0	R	-
4/4	PGR2A	MR2	MR1	MR0	SDR1	SDR0	SBR2	SBR1	SBR0	R	_
5/5	PGR3A	PBR3	PBR2	PBR1	PBR0	PAR3	PAR2	PAR1	PAR0	R	-
6/6	CBITSB	C14	C13	C12	C11	C10	C7	C6	C5	R	
7/7	PGR1B	SCR3	SCR2	SCR1	SCR0	SAR3	SAR2	SAR1	SAR0	R	
8/8	PGR2B	MR2	MR1	MR0	SDR1	SDR0	SBR2	SBR1	SBR0	R	-
9/9	PGR3B	PBR3	PBR2	PBR1	PBR0	PAR3	PAR2	PAR1	PAR0	R	-
10/A	НАММС	HC7	HC6	HC5	HC4	нсз	HC2	HC1	нсо	R	FF
17/11	RDATA	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	R	_
18/12	EXTEND	APIIA	APIIB	RSIND	_	CLSI	ОИН	С9В	C9A	R	-
31/1F	STATUS	SL2	SL1	SL0	SR4	SR3	SR2	SR1	SR0	R	_
		L	L	1		L		I	<u> </u>	1	L

Table 1. Register details

WRITE REGISTERS

RADD
A17–16 Memory address
IAI Inhibit auto increment
RA5–0 Register address

ACON A/B

ACQ Acquisition on MGC Magazine compare PBC Page tens compare PAC Page units compare Sub-code compare digit D SDC SCC Sub-code compare digit C SBC Sub-code compare digit B Sub-code compare digit A SAC HLD Hold display

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PGS 1,2,3 A/B

SAS3-0 Sub-code digit A (LSD) select
SBS2-0 Sub-code digit B select
SCS3-0 Sub-code digit C select
SDS1-0 Sub-code digit D (MSD) select
PAS3-0 Page (units) select

PBS3–0 Page (trins) select
MS2–0 Magazine select

RECON

WIO Write inhibit packet 0
WI24 Write inhibit packet 24
WI25 Write inhibit packet 25

PINB Parity check inhibit Acquisition B
PINA Parity check inhibit Acquisition A
FF Full Field mode

CDB Clear store disable Acquisition B
CDA Clear store disable Acquisition A

DISCON1

INV Invert display colours
RLH Roll headers

DSB Display acquisition circuit B (A if zero)

CLS Clear current display store

CUR Cursor enable
BLC Block cursor
LS3 Language group select
UDI Display update indicator

DISCON2

LS2-0 Language select
MGS Magazine serial
IHD Inhibit display rows 1-25
SPH Suppress header
BX1-0 Boxing control bits

DISCON3

TXT Text/ not picture
MIX Mix text and picture
INT Text interlace sync mode
REV Reveal hidden text

UDK Update key – inhibit rows 0-25 SPOS Status line 2 position, top if set high

ST2 Display status line 2 ST1 Display status line 1

DISCON4

BXP Box page number
BXH Box header
BXT Box time
BXS Box status rows
DHT Double height top
DHB Double height bottom
SG2-1 Separated graphics control bits

HADD & LADD

A15–0 Memory address

WDATA

WD7–0 Write data byte to memory

SCROLL

WI29 Write inhibit packet 29 MV Majority vote on framing code

CRL Cursor lock

SRA4-0 Scroll value 0-23 only

SYNCSW

ESS External sync source

BXSDEL Box status delay by one character

CSOT CSO TTL signal
IOE Interlace output enable
EOE Even output enable
SEN Select enable SVS

SVS Select VSI input as sync source

MODE

MD3 H sync mode 3 MD2 H sync mode 2 MD1 H sync mode 1

912:313 Non-interlace 312:313 mode VHLD Vertical sync half line delay (Fig. 9)

HVEN H and V inputs enable

HINV H invert VINV V invert

TADD

A18 Memory address
RESET Reset to default state

XCKH XCK output 13.875MHz or 6.9375MHz when low

2K/ST 2K/store mode

DISC Disconnect display from acquisition
ADEC Automatic memory decrement
DST8 Store number for display bit 8

DISPST DST7-0

Store number for display bits 7-0

DPOS

V3–0 Vertical position in 2 line steps H3–0 Horizontal position in 4 pixel steps

ENABLE

NPR Enable NPR flag in read regs VHR Enable VHR flag in read regs Enable 830 flag i read regs 830 Enable X/24A flag in read regs X/24A X/28 Enable X/28 flag in read regs X/27 Enable X/27 flag in read regs X/26 Enable X/26 flag in read regs X/24B Enable X/24 flag in read regs

ACCENT

APA-B Accent protection A/B

C8APIA-B C8 accent protection inhibit A/B SCAPIA-B Sub-code accent protection inhibit A/B

AHEN Advanced headers enable

READ REGISTER

E۷	E	N	Т	A	Έ

NPR VHR 830A 830B X/24 X/28 X/27 X/26 C8	New page received flag Valid header received flag Packet 8/30 format 1 received flag Packet 8/30 format 2 received flag Packet X/24 received flag Packet X/28 received flag Packet X/27 received flag Packet X/26 received flag Packet X/26 received flag Update indicator	RDATA RD7-0 CBITS A/B C14-12 C11 C10 C7 C6 C5	Read data byte from memory Language select bits (C14 is LSB) Magazine serial Inhibit display Suppress header Sub-title News flash
PGR 1,2,3 A/B SAR3-0 SBR2-0 SCR3-0 SDR1-0	Sub-code digit A (LSD) received Sub-code digit B received Sub-code digit C received Sub-code digit D (MSD) received	HAMMC HC7-0 EXTEND APII A/B RSIND	Hamming counter Accent protection inhibit indication A/B Reset indication
PAR3-0 PBR3-0 MR2-0	Page (units) received Page (tens) received Magazine received	CLSI ONH C9 A/B STATUS SL2-0 SR4-0 SL2-0=003	Clear screen indicator On hours flag Interrupted sequence bit Acq A/B Status language indication Status revision indication All Europe version

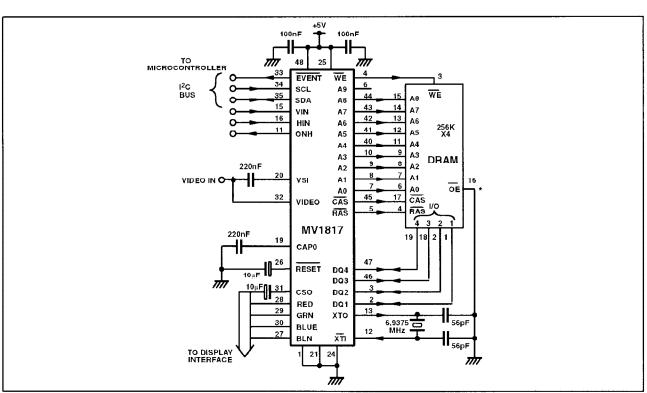


Fig. 3 Typical application diagram

I²C bus Interface – SCL and SDA.

Control of the MV1817 registers is through this interface. The I²C bus address is 0010 001 R/W

The circuit works as a slave transmitter with bit eight set high or as a slave receiver with bit eight set low. In receive mode, the first data byte is written to RADD register, where the least significant five bits form the sub-address. The most significant three bits of RADD are data bits, see Table 1.

Automatic incrementing of the registers allows successive data bytes to be written to, or read from the registers. The automatic incrementing can be disabled by setting IAI bit five of RADD to one. Automatic increment can be changed to

automatic decrement (for DRAM address NOT registers) by setting ADEC bit high in TADD register. All DRAM addresses may be accessed via the I²C bus interface.

When WDATA or RDATA registers are reached, the automatic incrementing accesses successive bytes of data in the DRAM starting from the current value of HADD and LADD. Automatic incrementing of registers will operate above WDATA from SCROLL register onwards.

^{*} Note, on some DRAM devices OE should not be low during a write cycle. An inverted WE can be connected to OE in such cases.

MEMORY MAPS

The DRAM memory as viewed from the I²C bus is organised in 1024 (400hex) byte blocks, referred to as a store. Stores 0 and 1 in 1K/store mode are reserved for the non-display packets from acquisition A and B respectively. Stores A0 and B0 in 2K/store mode are reserved for the

packets X/29 and 8/30 from acquisition A and B respectively. The table below shows the start addresses for each store. The store numbers relate to the values in the STORA, STORB and DISPST registers.

1K/store	Start addresses hex TADD, RADD, HADD, LADD	2K/store
STORE 0	0 0 00 00	STORE A0
STORE 1	0 0 04 00	STORE B0
STORE 2	0 0 08 00	STORE 1 DISPLAY
STORE 3	0 0 00 00	STORE 1 EXT PKTS
STORE 4	0 0 10 00	STORE 2 DISPLAY
STORE 5	0 0 14 00	STORE 2 EXT PKTS
STORE 6	0 0 18 00	STORE 3 DISPLAY
STORE 7	0 0 1C 00	STORF 3 EXT PKTS
	etc. until	
STORE 508	1 3 F0 00	STORE 254 DISPLAY
STORE 509	1 3 F4 00	STORE 254 EXT PKTS
STORE 510	1 3 F8 00	STORE 255 DISPLAY
STORE 511	1 3 FC 00	STORE 255 EXT PKTS

Table 2 Memory organisation

First byte Relative Address hex				Last byte Relative Address hex
00000	NOTE 1	PACKET 0 24 bytes	NOTE 2	00017
00018		PACKET 1 40 bytes	•	0003F
00040				
00068				
00090				
000B8				
000E0	Ĭ			
00108	1			
00130	İ			
00158				
00180	İ			
001A8			*	
001D0	İ		İ	
001F8				
00220	1			
00248				
00270				
00298				
002C0				
002E8				
00310				i
00338				
00360				
00388				003AF
003B0		PACKET 24	····	003D7
003D8		PACKET 25		003FF

Fig. 4. Organiation of DISPLAY memory

- Note 1. Page number, 8 bytes from store 0 (A0) with absolute addresses 000 to 007
- Note 2. Time display, 8 bytes from store 0 (A0) with absolute addresses 008 to 00F $\,$

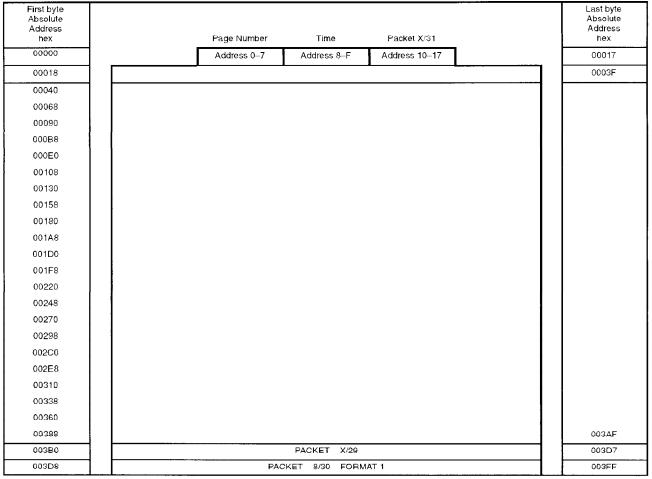


Fig. 5. Store 0 (A0) Memory organisation.

NOTE: Store 1 (B0) is organised similarly except that, in 1K/store mode it accepts acquisition circuit B packets X/26 etc. and packet 8/30 format 2 in the last row. To obtain addresses for store 1 (B0) add 400hex. Bytes 400 to 417hex are not used in store 1 (B0).

In 2K/store mode, all page related extension packets, X/26, X/27 and X/28, are directed to the store adjacent to the display store, see Table 2. Up to 23 of these packets are stored in the order received with no fixed location in the memory. The first four bytes with relative address 000 to 003 contain a copy of the related acquisition circuit data in CBITS and PGR1-3 registers in the same order. Bytes 004 to 017_{hex} are not used by the MV1817. The last two rows will not be used by the MV1817 since X/29 and 8/30 packets only go to stores A0 and B0 (or to stores 0 and 1 in 1K/store mode).

Synchronisation

In the usual configuration where a video signal is applied to the data and sync slicer, a composite sync output (CSO) is generated from the sliced video input. CSO can be modified by register bits to provide 312:312, 312:313 or 312.5:312.5 text syncs, or switch through the video switch input signal direct. If video syncs are selected with SEN=1 and SVS=1 (in SYNCSW register), the action of the 312:313 bit (in MODE register) is inhibited.

When the vertical synchronisation circuit finds a field sync datum, (see Fig. 6) it is disabled for 64 lines so that double field synchronisation is avoided.

If the display is to be synchronised to horizontal and vertical

signals via the HIN and VIN pins, the HVEN enable bit in the MODE register must be set high. This will disable the action of interlace (INT) bit in DISCON3 register and also 312:313 bit in MODE register. HIN and VIN signals are normally positive pulses, but inverted signals may be applied provided that the appropriate HINV and VINV bits are set high in the MODE register. The leading edge of VIN pulse is sampled at –4.7µs and +27.3µs with respect to HIN pulse to establish which is the EVEN or ODD field, see Fig. 7. The VIN pulse should be at least 32µs minimum and the HIN pulse 1µs minimum.

If required, the vertical pulse may be delayed by half a line period by setting VHLD bit high in MODE register, see Fig. 8.

LS(3210)	0000	0001	0010	0011	0100	0101	0110	0111
TABLE POSITION	ENGLISH	GERMAN	SWEDISH FINNISH	ITALIAN	FRENCH (BELGIAN)	SPANISH	CZECH	ROMANIAN
2/3	Æ	#	#	£	é	ç	#	#
2/4	\$	\$	¥	\$	ï	\$	ů	\$
4/0	ē	5	É	é	à	i	č	Ţ
5/B	←	Ä	Ä	۰	ë	á	ť	A
5/C	12	ö	Ö	ç	ê	é	ž	ş
5/D	→	Ü	Â	→	ù	í	ý	Ă
5/E	1	^	Ü	↑	î	ó	í	Ì
5/F	#			#	#	ú	ř	1
6/0		٥	é	ù	è	ė	é	ţ
7/B	14	ä	ä	à	â	ü	á	â
7/C		ö	ö	ò	ô	ñ	ě	5
7/D	34	ü	â	è	û	è	ú	ă
7/E	÷	ß	ü	ì	ç	ā	š	î

LS(3210)	1000	1001	1010	1011	1100	1101	1110	1111
TABLE POSITION	POLISH	GERMAN	HUNGARIAN	TURKISH	DANISH	SERBO CROAT	CZECH	SOUTH AFRICAN
2/3	#	#	#	TL	£	#	#	£
2/4	ń	\$	ú	ğ	\$	\$	û	\$
4/0	ą	5	É	İ	@	č	č	'n
5/B	Z	Ä	í	Ş	Æ	ć	ť	ë
5/C	5	ö	Ö	Ö	Ø	ž	ž	ê
5/D	Ł	Ü	Á	Ç	Â	Ð	ý	ü
5/E	ć	٨	ű	Ü	1	Š	í	é
5/F	ó		ő	Ğ	#	ë	ř	ï
6/0	ę		é	1		č	é	š
7/B	ż	ä	ó	ş	æ	ć	á	ä
7/C	Ś	ö	ö	ö	Ø	ž	ě	ô
7/D	ł	ü	á	ç	â	đ	ú	ů
7/E	ź	ß	ü	ü	-	š	Š	ö

Table 3 Narional Optional Characters. Language version 003.

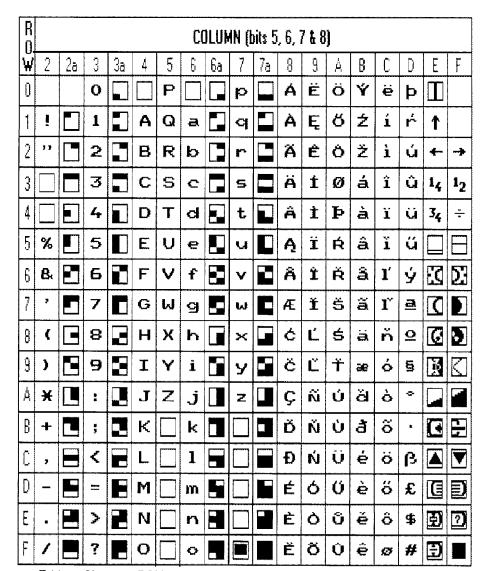


Table 4. Character ROM contents as viewed by the display. Language version 003.

Notes: Character positions F0 and F1 will be displayed as spaces, but are actually spacing control codes, like the control columns 0 and 1 listed in table 6.

FO is UNDERLINE start / stop code.

F1 is INVERT display colours start / stop code.

FF is displayed as all foreground.

☐ Characters in these positions are displayed according to the setting of LS(0-3) bits, see table 3.

When graphics mode is set, columns 2a, 3a, 6a & 7a are displayed as the graphic symbols shown with black as forground colour. All other columns are displayed normally. The graphic symbols are shown above with a border which is not present when the symbol is displayed on the screen.



Graphic symbols to scale

Page closure.

In serial mode, any header will close a page being received.

In parallel mode, only a header from the selected magazine will close a page being received.

Advanced Header and Instant Page Clear transmission systems.

With these systems, the main page header packet is transmitted in the same VBI, before the associated data packets, without the standard 20ms page clearing interval. The MV1817 can be programmed to protect those associated data packets, in the same VBI, from erasure when the page is cleared. This feature is enabled for both systems by setting AHEN bit high in ACCENT register.

	INCLUDED IN MV1817- 3	NOT INCLUDED
CZECH	ÄÁČĎÉĚÍĹĽŃŇÖÓÔŔŘŠŚŤÜÚŮÝŹŽß§° ä ď ľľňöóôŕ ü	
DENMARK	Ææ Øø	
FRANCE	ÀÂÇÈÉÊËÏÎÔÛ	Œœ
HOLLAND	Ëë	IJij
HUNGARY	ÁÍÓŐÚŰ	
	á í ó ő ú ű	
ICELAND	ÁÐ ÍÓÖÞÚÝÆØ ð öþýæø	
ITALY	ÀÈÉ ÌÍ Ò Ù Ú Í Ú	
POLAND	ĄĆĘŃÓŹ\$§_	
ROMANIA	ÉĚĚĬÓ	
	é ě ê ĭ ó	
SPAIN	ÁÀÃ ÇÉÈ ÏÍÑÓ Ò ÕKÚÜ#'*°→⊺ ãaâ ëêïî ôòööf û	
TURKEY	ÂÎÛ	
	âîû	

Table 5. Additional characters for the languages shown. Language version 003.

Accented characters added via X/26

These can be automatically locked in place on the screen by the MV1817 hardware, so that further reception of the page will not change accented characters to the level one fall-back characters. Whenever a page is cleared to spaces, the locked characters will be unlocked and also become spaces. Control of this feature is by setting APA/B bits in ACCENT register. The header should be cleared by software the first time a store is used to prevent random characters in the DRAM at power up

from being locked. For pages where data is updated with C8 set, but clear page C4 is not set, the accent locking feature may be inhibited during current page reception by setting C8ÁPIA/B bits. For rolling sub-coded pages where clear page C4 is not set, the accent locking feature may be inhibited during current page reception by setting SCAPIA.B bits. When these inhibit mechanisms are active, an indication is provided in EXTEND register by bits APIIA/B set high. They are set low when the current page is closed.

	0	1		
0	Alpha Black	Graphic Black		
1	Alpha Red	Graphic Red		
2	Alph Green	Graphic Green		
3	Alpha Yellow	Graphic Yellow		
4	Alpha Blue	Graphic Blue		
5	Alpha Magenta	Graphic Magenta		
6	Alpha Cyan	Graphic Cyan		
7	Alpha White ¹	Graphic White		
8	Flash	Conceal Display ²		
9	Steady ^{1 2}	Contiguous Graphics ^{1 2}		
A	End Box ¹	Separated Graphics ²		
В	Start Box ³	No Action		
С	Normal Height ¹²	Black Background ^{1 2}		
D	Double Height	New Background ²		
Е	No Action	Hold Graphics		
F	No Action	Release Graphics		

Table 6. Control codes.

Notes:

- Presumed set at the start of each display row.
 Action "set at the current space", others are "set after the current space".
- 3. Two consecutive codes are transmitted, action takes place between them.

Sync switch register truth table

ESS	SEN	svs	CSO output	•
0	0	Х	VSI or digital sync selected by algorithm	
0	1	0	Digital syncs	
0	1	1	VSI switched through	
1	X	X	Digital syncs from SYNC I/O	

X=don't care.

Sync switch algorithm

The video signal will be switched through from VSI to CSO when: TXT = 0 or MIX = 1 or TXT = 1 and BX1 = 1 and BX0 = 1.

EVEN output on TEST pin, truth table

IOE	EOE	cso	Function
Х	0	Х	TEST configured as an input with an internal pull down resistor
0	1	INTERLACE	Enables EVEN output, which is held high.
1	1	INTERLACE	Enables EVEN output going high during the first field (lines 1-312½)
Х	1	312:313	Enables EVEN output going high during the short field (312 lines)

X = don't care.

Note:

CSO is not only dependent upon the state of the INT bit in DISCON4 register, but also on MIX and any other register bits which cause picture to be displayed, for example, UDK, BXP, BXH, BXT, BXS, or BX0-1 if start box codes are present on screen.

BOXING options and MIX mode, truth table

The bits BXP, BXH, BXT and BXS in DISCON4 register will BOX text into the picture when TXT and MIX mode are set, the BOXED text will retain its background colours. However, BOXED text using Box codes 0B in text together with BX0 or BX1 bits in DISCON2 will not override MIX and can be

displayed as BOXED text by setting TXT & MIX bits low, or MIXED by setting MIX high. The BOXED STATUS ROWS can start at character position one by setting BXSDEL bit in SYNCSW register.

TXT	BX-	- 1.0	BX – n	MIX	Status Area n	Boxed Text Areas		BASIC MODE
			(n=P, H, T, S)			Outside	Inside	
0	0.	.0	0	Х	Picture	Picture	Picture	DIATURE
0	0.	.0	1	0	Boxed	Picture	Picture	PICTURE
0	0.	.0	1	1	Mixed	Picture	Picture	
0	X.1	1.X	0	0	Picture	Picture	Text	
0	X.1	1.X	0	1	Picture	Picture	Mixed	NEWSFLASH
0	X.1	1.X	1	0	Boxed	Picture	Text	
0	X .1	1. X	1	1	Boxed	Picture	Mixed	
1	0.X	X.0	Х	0	Text	Text	Text	TEVT
1	0.X	X.0	0	1	Mixed	Mixed	Mixed	TEXT
1	0.X	X.0	1	1	Boxed	Mixed	Mixed	
1	1.	.1	Х	0	Text	Text	Picture	WINDOW
1	1.	.1	0	1 1	Mixed	Mixed	Picture	WINDOW
1	1.	.1	1	1	Boxed	Mixed	Picture	

X = don't care.

BOX STATUS DELAY

When status rows 1 and/or 2 are enabled to be boxed into a picture or MIX text display, the first character in the row may be omitted and replaced by picture by setting the BXSDEL bit 5 in SYNCSW register high

SCROLL

A value in the range 0-23 can be used to move the text rows 1-23 up the screen, the rows 0, 24 and 25 remain fixed.

A scroll value of 3 will cause text row 4 to be displayed in row 1. Text rows 1–3, in this example will appear in rows 21, 22 and 23 respectively. If half page expand is also used, by setting DHT in DISCON3 register, the text screen can be made to scroll through the expanded top half window. The position of the text in memory, is not affected by scroll, only the row addressing is changed to effect the display.

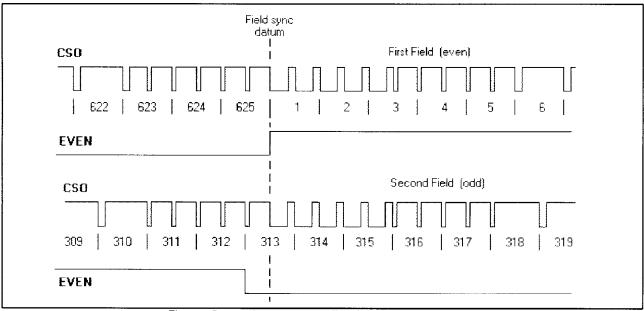


Fig. 6a. Composite sync output (interlaced) and EVEN output.

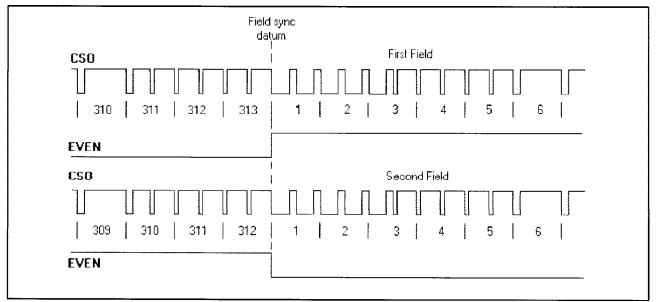


Fig. 6b. Composite sync output (non-interlaced 312:313) and EVEN output.

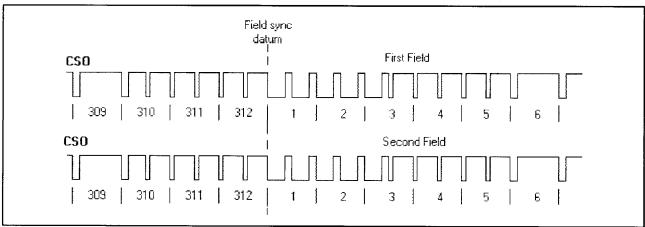


Fig. 6c. Composite sync output (non-interlaced 312:312).

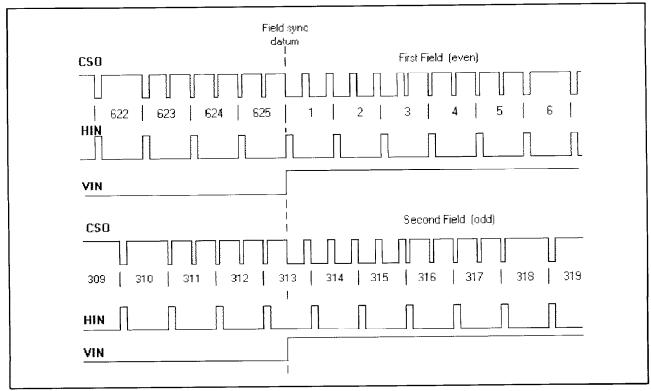


Fig. 7. Horizontal and Vertical input waveforms.

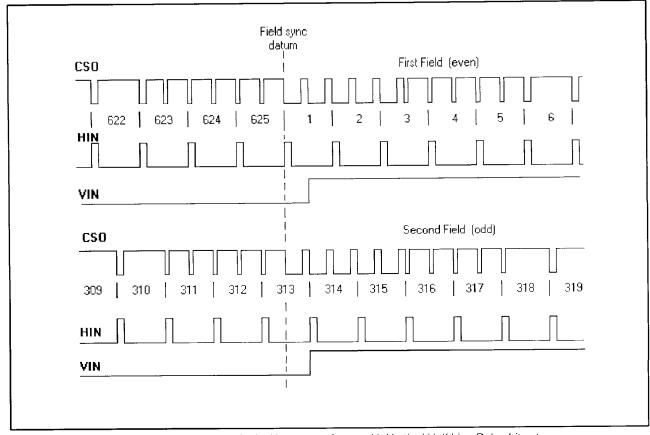


Fig. 8. Horizontal and Vertical input waveforms with Vertical Half Line Delay bit set.

• • •		Value for DRAM		Units
Symbol	Parameters Description	Min	Max	
t _{RAC}	Access time from RAS		<106	ns
†CAC	Access time from CAS		<43	ns
t _{CAA}	Access time from column address	*****	<61	ns
t _{CPA}	Access time from CAS precharge		<72	ns
t _{ASR}	Row address set-up time before RAS	<27		ns
t _{RAH}	Row address hold time after RAS	<45		ns
t _{RSH}	RAS hold time	<36		ns ns
t _{ASC}	Column address set-up time before CAS	<18	 	
[†] CAH	Column address hold time after CAS	<54		ns
t _{CRP}	CAS to RAS precharge time	<72		ns
t _{RCD}	RAS to CAS delay	<63		ns
t _{RP}	RAS precharge time	<81		ns
t _{CP}	CAS precharge time	<27 <45		ns ns
t _{CAS}	CAS low pulse width			
t _{RAS}	RAS low pulse width	<171		ns
t _{DS}	Data set-up before CAS	<18		ns
t _{DH}	Data hold time after CAS	<54		ns
twcs	Write set-up before CAS	<72		ns
^t wcH	Write hold time after CAS	<72		ns
t _{PC}	Page mode cycle time	<72		ns
t _{REF} – 64Kx4	Refresh cycle time per RAS address		>1.033	ms
t _{REF} – 256Kx4	Refresh cycle time per RAS address		>2.066	ms
t _{REF} – 1Mx4	Refresh cycle time per RAS address		>4.133	ms

Table 7. Timing parameter required for DRAM.

NOTE: Timings are for nominal center points on edges, so care should be taken not to load the pins.

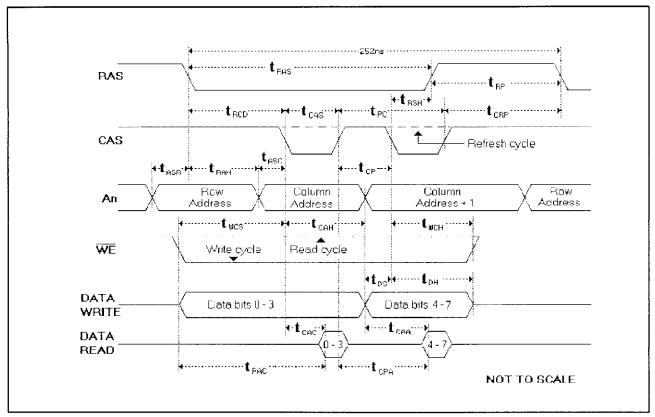


Fig. 9 DRAM interface.

DISPLAY STORE

The MV1817 has two modes of operation defined by the setting of DISC bit in TADD register.

1. With DISC set low, the display store is tied to acquisition circuit A, if DSB bit in DISCON1 register is low, or to acquisition circuit B if DSB bit is set high. STORA or STORB defines the working store for both acquisition and display.

2. With DISC set high, the display store is disconnected from the acquisition circuits and controlled independently by the DISPST register, together with DST8 in TADD register.

The store number programmed into STORA, STORB or DISPST registers is internally adjusted to take account of 2K/STORE working, see table 2. However, the I²C bus addresses for the DRAM data are NOT internally adjusted in 2K/STORE mode, see again table 2.

DISPLAY POSITION

This may be adjusted by changing the value in the DPOS register. The lower 4 bits control the horizontal position. The default state is Bhex and the step size is four pixels (0.288 μs). Incrementing by one moves the display right by four pixels. This means the display can be moved 16 pixels (1.153 μs) right and 44 pixels (3.171 μs) left from the default position 15.28 μs from leading negative edge of the Composite Sync Output horizontal sync pulse, see Fig. 10.

The upper 4 bits control the vertical position and the line numbers are referred to the Field Sync Datum on the Composite Sync Output, see Fig. 6. The default state is 7hex and the step size is 2 TV lines. Incrementing by one moves the display up two TV lines. The default start position is TV line 46 for a 24 row display and TV line 36 for a 25 or 26 row display. The range of movement is 16 TV lines up and 14 TV lines down from the default starting position, see Fig. 11.

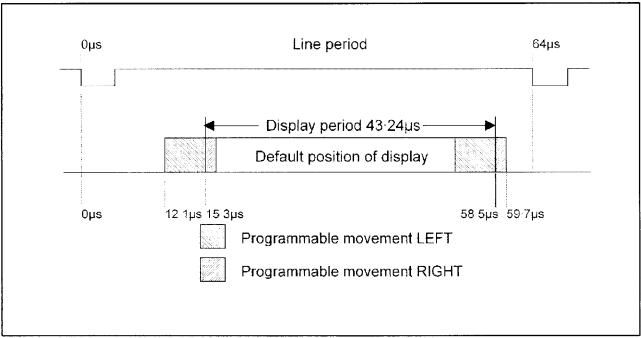


Fig. 10 Horizontal position and movement of text display.

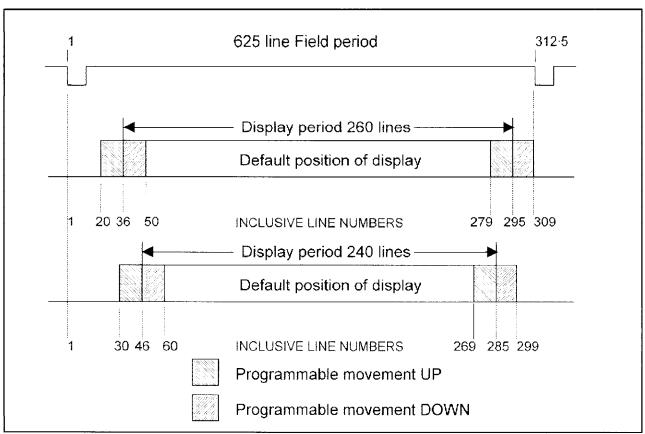


Fig. 11 Vertical position and movement of text display.



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